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[54] **EDGE MASKING SPIN TOOL**

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[58] **Field of Search** 118/52, 504, 505, 503, 118/409, 416

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[57] **ABSTRACT**

An apparatus and method for spin coating a substrate with a liquid material which prevents the material from contacting the edge or backside of the substrate or forming an edge bead at the periphery of the substrate is disclosed. A spin chuck is equipped with a conformable elastomer which seals the edge of the substrate and forms a continuous surface with a planar surface of the substrate for the liquid material to flow off the substrate unimpeded during the spin coating process. As the elastomer is resilient, small variations in substrate size and shape are automatically compensated. None of the substrate area is lost to masking and/or removal processes as in the prior art, allowing the entire substrate area to be available for further processing.

7 Claims, 4 Drawing Sheets